



Material Content Data Sheet



Sales Product Name		ESD311-U1-02N E6327		Issued		19. January 2018		
MA#		MA001213862						
Package		PG-TSNP-2-2		Weight*		1.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.105	5.58	5.58	55838	55838
leadframe	non noble metal	zinc	7440-66-6	0.002	0.10		1043	
	non noble metal	tin	7440-31-5	0.002	0.13		1304	
	non noble metal	chromium	7440-47-3	0.003	0.16		1565	
wire	non noble metal	copper	7440-50-8	0.974	51.81	52.20	517877	521789
	non noble metal	copper	7440-50-8	0.003	0.17	0.17	1748	1748
encapsulation	organic material	carbon black	1333-86-4	0.003	0.17		1731	
	plastics	epoxy resin	-	0.094	5.02		50192	
	inorganic material	silicondioxide	60676-86-0	0.554	29.42	34.61	294232	346155
leadfinish	non noble metal	tin	7440-31-5	0.055	2.90	2.90	29039	29039
plating	noble metal	silver	7440-22-4	0.022	1.17	1.17	11708	11708
glue	plastics	epoxy resin	-	0.013	0.67		6744	
	noble metal	silver	7440-22-4	0.051	2.70	3.37	26979	33723
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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